

## LM113/LM313

.M113/LM313 Reference Diode

# **Reference Diode**

#### **General Description**

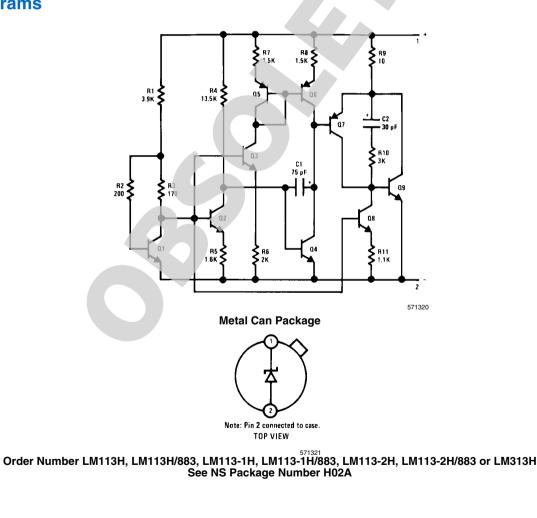
The LM113/LM313 are temperature compensated, low voltage reference diodes. They feature extremely-tight regulation over a wide range of operating currents in addition to an unusually-low breakdown voltage and good temperature stability.

The diodes are synthesized using transistors and resistors in a monolithic integrated circuit. As such, they have the same low noise and long term stability as modern IC op amps. Further, output voltage of the reference depends only on highlypredictable properties of components in the IC; so they can be manufactured and supplied to tight tolerances.

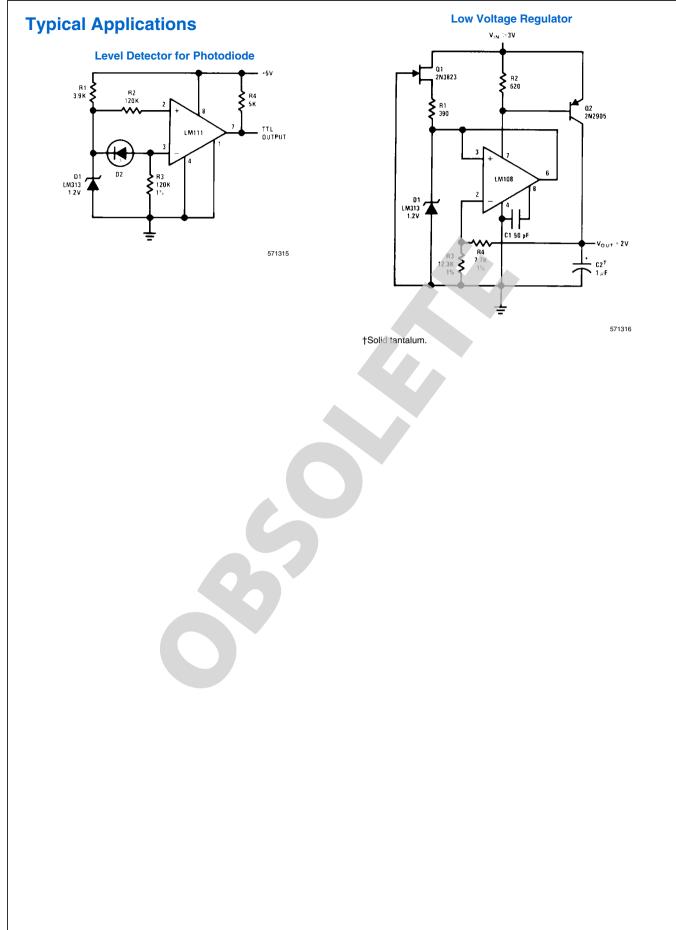
# Schematic and Connection Diagrams

#### **Features**

- Low breakdown voltage: 1.220V
- Dynamic impedance of 0.3Ω from 500 µA to 20 mA
- Temperature stability typically 1% over-55°C to 125°C range (LM113), 0°C to 70°C (LM313)
- Tight tolerance: ±5%, ±2% or ±1% The characteristics of this reference recommend it for use in bias-regulation circuitry, in low-voltage power supplies or in battery powered equipment. The fact that the breakdown voltage is equal to a physical property of silicon —the energy-band gap voltage—makes it useful for many temperature-compensation and temperaturemeasurement functions.







#### Absolute Maximum Ratings (Note 3)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Power Dissipation ( <i>Note 1</i> )	100 mW
Reverse Current	50 mA
Forward Current	50 mA

#### Electrical Characteristics (Note 2)

Parameter	Conditions	Min	Тур	Max	Units
Reverse Breakdown Voltage					
LM113/LM313	I <sub>R</sub> = 1 mA	1.160	1.220	1.280	V
LM113-1		1.210	1.22	1.232	V
LM113-2		1.195	1.22	1.245	V
Reverse Breakdown Voltage	0.5 mA ≤ I <sub>B</sub> ≤ 20 mA		6.0	15	mV
Change					
Reverse Dynamic Impedance	I <sub>R</sub> = 1 mA		0.2	1.0	Ω
	I <sub>R</sub> = 10 mA		0.25	0.8	Ω
Forward Voltage Drop	l <sub>F</sub> = 1.0 mA		0.67	1.0	V
RMS Noise Voltage	10 Hz ≤ f ≤ 10 kHz		5		μV
	I <sub>R</sub> = 1 mA				
Reverse Breakdown Voltage	0.5 mA ≤ I <sub>B</sub> ≤ 10 mA			15	mV
Change with Current	$T_{MIN} \le T_A \le T_{MAX}$				
Breakdown Voltage Temperature	1.0 mA ≤ I <sub>B</sub> ≤ 10 mA		0.01		%/°C
Coefficient	$T_{MIN} \le T_A \le T_{MAX}$				

Note 1: For operating at elevated temperatures, the device must be derated based on a 150°C maximum junction and a thermal resistance of 80°C/W junction to case or 440°C/W junction to ambient.

**Note 2:** These specifications apply for  $T_A = 25^{\circ}$ C, unless stated otherwise. At high currents, breakdown voltage should be measured with lead lengths less than 1/4 inch. Kelvin contact sockets are also recommended. The clode should not be operated with shunt capacitances between 200 pF and 0.1 µF, unless isolated by at least a 100 $\Omega$  resistor, as it may oscillate at some currents.

Note 3: Refer to the following RETS drawings for military specifications: RETS113-1X for LM113-1, RETS113-2X for LM113-2 or RETS113X for LM113.

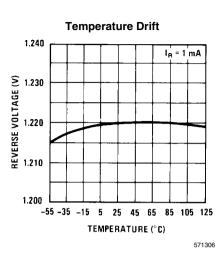
Storage Temperature Range-65°C toLead Temperature<br/>(Soldering, 10 seconds)-55°C toOperating Temperature Range<br/>LM113-55°C toLM3130°C tr

LM113/LM313

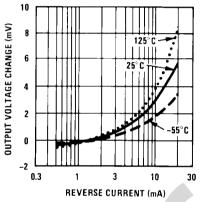
-55°C to+125°C 0°C to +70°C

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### **Typical Performance Characteristics**

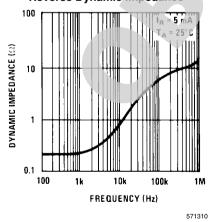




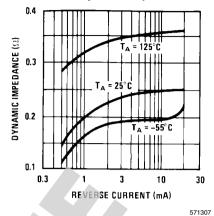


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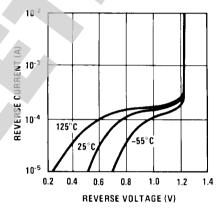
Reverse Dynamic Impedance



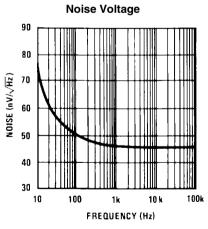




**Reverse Characteristics** 

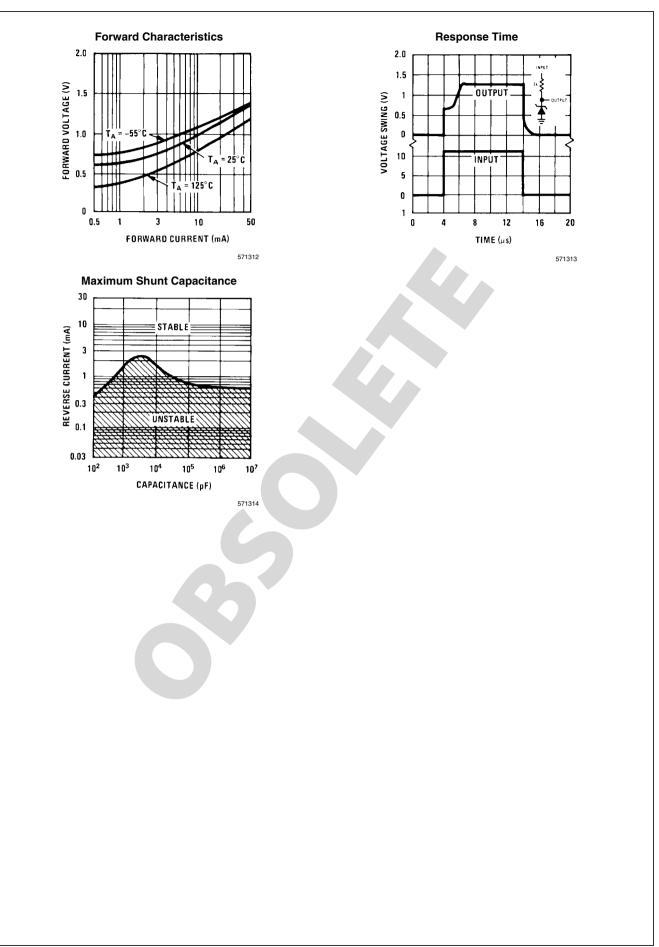


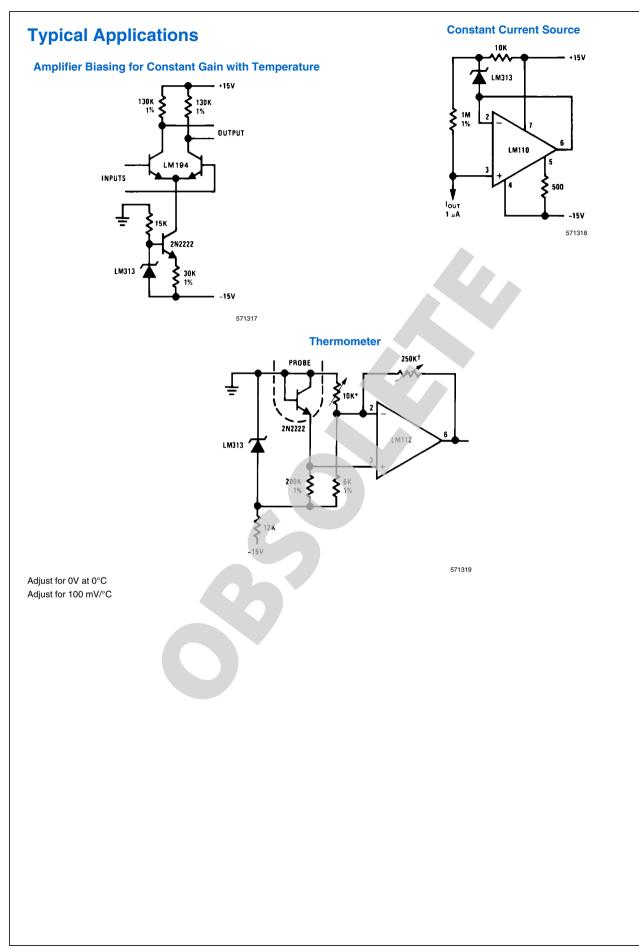
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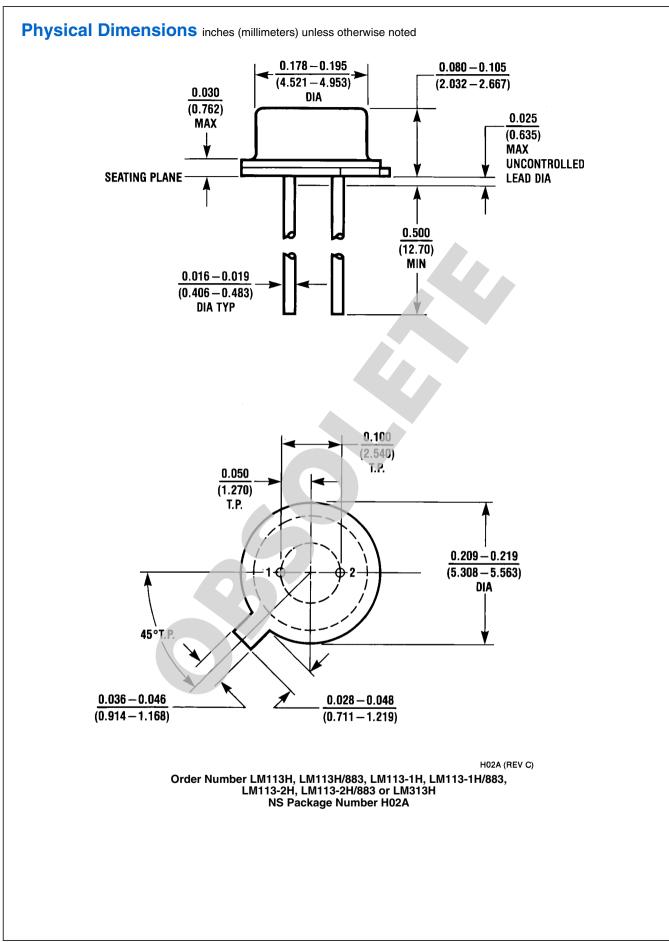


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